## ABSTRACT OF THE DISCLOSURE

HIGH DENSITY, THREE-DIMENSIONAL INTEGRATED CIRCUIT MODULE AND ELEMENTS FOR MAKING SAME

A stacked, three-dimensional module (12) of integrated circuits (10) is formed by first inserting circuit packages (10) into opposite ends of a conformal opening (34) in an electrically insulative, torroidal member (32) until their bodies (14) abut and their leads (18) engage conductive areas (52) on the member (32). Selected leads (18) and areas (52) are mechanically and electrically bonded together. Another member (32) may then be associated with one of the foregoing circuit packages (10) and an additional circuit package (10) in the same way. The process continues until a module (12) with the desired number of circuit packages (10) is formed. The module (12) may be terminated with end-pieces (60, 62), one (60) of which interconnects selected leads (18) of the topmost circuit package (10) and the other of which performs a similar interconnecting function for the bottommost circuit package (10) and permits the module (12) to be surface mountred to a mother board or the like.



This Sheet Has Been Replaced

